

SCRUBBING BRUSH WITH LIGAND ATTACHMENTS

Abstract of the Disclosure

A semiconductor wafer cleaning brush may have ligands attached along the length of its polymer chain. These ligands may provide moieties with specific functional
5 features such as providing a hydrophilic characteristic, a hydrophobic characteristic, a reducing agent, or an oxidizing agent, to mention a few examples. In addition, the attaching ligand may provide a mechanical cleaning structure that is effective in reaching into small areas on
10 the wafer to be cleaned. The ligand may be attached to the length of the brush polymer using a hydrolysis reaction in one embodiment.